

IN THE ABSTRACT

Please delete the current Abstract in its entirety and  
substitute therefor the enclosed New Abstract.

NEW ABSTRACT

A camera module includes a semiconductor housing that contains a solid-state image sensor with a radiation-sensitive surface area, and an optical element located above the solid-state sensor and which forms a shield against laterally scattered radiation. The optical element includes a disk-shaped body with a primary radiation-opaque area and a secondary radiation-transparent area located within the primary area, of which a surface close to the sensor is smaller than a surface more remote from the sensor. The optical element further includes a transparent plate of which two sides are covered with a radiation-opaque layer which is provided with an aperture. In the aperture, the layer close to the sensor has a smaller surface than the aperture in the layer located remote from the sensor.